II. Company Profile

1. MediaTek Company Profile

MediaTek Inc. was founded on May 28, 1997 and listed on the Taiwan Stock Exchange (TSE) in July 2001. The Company is headquartered in Taiwan, with sales and research subsidiaries in Singapore, Mainland China, Hong Kong, India, United States, Japan, Korea, England, Finland, Sweden, France, Holland and Dubai.

With continuous investments in advanced process and technologies, the Company is aiming for first mover opportunities in AI (artificial intelligence) and 5G to provide chipset solutions across platforms, including smart home, connectivity, IoT and wearable, automotive, ASIC and handset devices as well as enable global customers to innovate and provide higher value products and services. MediaTek has a leading position globally and possesses competitive edge.

By building technologies that help connect individuals to the world around them, the Company is enabling people to expand their horizons and more easily achieve their goals. We believe anyone can achieve something amazing. And we believe they can do it every single day. We call this idea Everyday Genius and it drives everything we do.

2. Milestones

Year	Milestones
2019	■ Won IoT Breakthrough "IoT Semiconductor Company of the Year" Award ■ MediaTek Helio P90 honored as Winner of "Compass Intelligence Tech Awards" given by Compass Intelligence ■ MediaTek Helio P60 honored as Gold Winner of "Golden Mousetrap Award" given by Design News ■ MediaTek Helio P60 chosen as the Finalist of "Electronic Products Product of the Year Award" given by Digital ICs ■ MediaTek NB-IoT chipset MT2625 chosen as the Finalist of "Best IoT Connectivity Solution Award" given by IoT World ■ Published 8 papers in ISSCC and hit a new record of papers selected by ISSCC for 16 consecutive years among Taiwan companies – "6.4 A 180mW 56Gb/s DSP-Based Transceiver for High-Density IOs in Data Center Switches in 7nm FinFET Technology", "18.1 A -105dBc THD+N (-114dBc HD2) at 2.8VPP Swing and 120dB DR Audio Decoder with Sample-and-Hold Noise Filtering and Poly Resistor Linearization Schemes", "A 40MHz-BW 320MS/s Passive Noise-Shaping SAR ADC with Passive Signal-Residue Summation in 14nm FinFET", "20.4 An 8×-OSR 25MHz-BW 79.4dB/74dB DR/SNDR CT DS Modulator Using 7b, Linearized Segmented DACs with Digital Noise-Coupling-Compensation, Filter in 7nm FinFET CMOS", "20.6 An 80MHz-BW 31.9fJ/conv-step Filtering DS ADC with a Built-In DAC-Segmentation/ELD-Compensation 6b 960MS/s SAR-Quantizer in 28nm LP for 802.11ax Applications", "An LTE-A Multimode Multiband RF Transceiver with 4RX/2TX Inter-Band Carrier Aggregation, 2-Carrier 4×4 MIMO with 256QAM and HPUE Capability in 28nm CMOS", "An 8b Injection-Locked Phase Rotator with Dynamic Multiphase Injection for 28/56/112Gb/s Serdes Application", and "Data Converter Design Considerations for Mobile Transceivers: Benchmark and Trends from 4G LTE to 5G NR"
2018	■ Received "Outstanding Asia-Pacific Semiconductor Company" Award from Global Semiconductor Alliance (GSA) ■ Selected as "Taiwan Top 10 Global Brands", hosted by Ministry of Economic Affairs and Interbrand for the fourth consecutive year ■ Won TCSA "Top 50 Corporate Sustainability Award"; also received "Top 50 Corporate Sustainability Platinum Award", "People Development Award", "Growth through Innovation Award," "Social Inclusion Award" and "Supply Chain Management Award" for the Manufacturing industry ■ Ming-Kai Tsai, MediaTek Chairman, chosen as one of Harvard Business Review's "Top 50 the Best CEOs in Taiwan ■ MediaTek Helio P60, awarded by Android Authority, as the best of MWC 2018 ■ Published 4 papers in ISSCC and hit a new record of papers selected by ISSCC for 15 consecutive years among Taiwan companies – "An 87.1% Efficiency RF-PA Envelope Tracking Modulator for 80MHz LTE- Advanced Transmitter and 31dBm PA Output Power for HPUE in 0.153μm CMOS", "A 0.0004% (-10BdB) THD+N 112dB SNR and 3.15W Fully Differential Class-D Audio Amplifier with Gm Noise Cancellation and Negative Output Common Mode Injection Techniques", "A 50MHz-BW Continuous -Time lll: ADC with Dynamic Error Correction Achieving 79.8dB SNDR and 95.2dB SFDR (Co-author with Oregon State University)", and "94% Power-Recycle and Near-Zero Driving-Dead-Zone N-type LowDropout Regulator with 20mV Undershoot at Short-Period LoadTransient of Flash Memory in Smart Phone" ■ Received the awards of "2018 all Asia Executive team" on top-ranked company for CEO, CFO, IR Professional, IR Program, Analyst Days and Website" from "Institutional Investor Magazine"

Year	Milestones
2017	■ Selected as “Taiwan Top 10 Global Brands”, hosted by Ministry of Economic Affairs and Interbrand for the third consecutive year ■ Received Taiwan Corporate Sustainability Awards’ highest honor for the very first time, namely, “The Most Prestigious Sustainability Awards-Top Ten Domestic Corporate “, as well as its “Top 50 Corporate Sustainability Report Award”, “Growth through Innovation Award”, “Social Inclusion Award” and “Supply Chain Management Award” ■ Rated by Forbes as one of “Top Multinational Performers” and “Growth Champions” as well as “Asia's Fab 50 Companies” ■ Awarded “Top 100 Applicants” by European Patent Office (EPO) for the third consecutive year. ■ Received award of ”Foreign Direct Investment Company of the Year 2017” from City of Oulu, Finland ■ Listed in PwC's “The 2017 Global Innovation 1000 Study” as one of the world's top corporate R&D investors ■ Selected as FTSE4Good Index component ■ MediaTek HEVC codec won 2017 Primetime Emmy Engineering Award ■ MediaTek Helio X30 honored as “Innovation Product Award and R&D Accomplishment Award (Integrated Circuit)” by Hsinchu Science Park Bureau ■ Published 10 papers in ISSCC and hit a new record of number of papers selected by ISSCC among MediaTek’s history, Taiwanese companies and global semiconductor companies – “A high-efficiency multi-band Class-F power amplifier in O.1531Jm bulk CMOS lor WCDMA/LTE applications”, “A 0.46mW 5MHzBW79.7dB SNDR Nolse•Shaping SAR ADC with Dynamic FIR-IIR Filter”, “A 10nm FinFET 2.8GHz, Tri-gear Deca-core CPU complex with optimized Power-delivery network for Mobile SoC Performance”, “An 802.11ac 5tage2(80+80) Dual-Band Reconfigurable Transceiver Supporting up to FourVHTBO Spatial Streams with 116f5 JitterRMS Frequency Synthesizer & Integrated LNAJPA Delivering 256QAM 19dBm per Stream Achieving 1.733Gbps PHY Rate”, “An Intelligent Low Power Transceiver Design for LTE-A Carrier Aggregation”, “A +8dBm BLElBT Transceiver with Automatically Calibrated Integrated RF Band-Pass Filter and -58dBc TX HD2”, “A 125MHz BW, 74.BdB DR, 71.9dB SNDR, -BOdBc THD, VCO-Based CT A:r. ACe with Phase-Domain ELD Compensation using 128- State Segmented Rotator in 16nm CMOS S-”, “A Fully Integrated Multi-Mode TxM for GSMIEDGElTD-SCDMAITDLTE Applications Using A Class-F CMOS Power Amplifier”, ”A Digitally Assisted CMOS WiFI802.11ac/11ax Front-End Module Achieving 12% PA Efficiency at 20dBm Output Power with 160MHz 256QAM OFDM Signal”, and “A high-linearity CMOS receiver achieving +44dBm IIP3 and +13dBm B1dB for SAW-less LTE radio” ■ Acquired Airoha Technology Corp.
2016	■ Awarded “Top 100 Global Innovators 2016” by Clarivate Analytics (formerly Thomson Reuters) for the third consecutive year ■ Received “Outstanding Asia-Pacific Semiconductor Company Award” from Global Semiconductor Alliance (GSA) for the fifth consecutive year ■ Selected as “Taiwan Top 10 Global Brands 2016”, hosted by Ministry of Economic Affairs and Interbrand for the second consecutive year ■ Mr. Ming-Kai Tsai, MediaTek Chairman and CEO, was honored by Harvard Business Review as one of “100 Best-Performing CEOs in the World” ■ Won “Taiwan Corporate Sustainability Awards 2016 – Electronics Industry” Gold Medal from Taiwan Institute for Sustainable Energy (TAISE) and “Supply Chain Management Awards” as well as “Growth through Innovation Awards” for the first time ■ Selected as “Most Admired Company Top 10”, hosted by CommonWealth Magazine and Mr. Ming-Kai Tsai, MediaTek Chairman and CEO, was honored as one of the “Most Admired Entrepreneurs” ■ Published 6 papers in ISSCC and hit a new record of papers selected by ISSCC for 13 consecutive years among Taiwan companies – “A 20nm, 2.5GHz, UltraLow Power TriCluster CPU Subsystem with Adaptive Power Allocation for Optimal Mobile SoC Performance”, “A 10MHzbandwidth, 4µs largesignal settling, 6.5nV/vHz noise, 2µVoffset Chopper Operational Amplifier”, “A Dual-Band Digital-WiFi 802.11a/b/g/n Transmitter SoC with Digital I/Q Combining and Diamond Profile Mapping for Compact Die Area and Improved Efficiency in 40nm CMOS”, “A 160MHz BW, 72dB DR, 40mW Continuous Time DeltaSigma Modulator in 16nm CMOS with Analog ISIReduction Technique”, “An Oversampling SAR ADC with DAC Mismatch Error Shaping Achieving 105dB SFDR and 101dB SNDR over 1kHz BW in 55nm CMOS”, and “A 0.35mW 12b 100MS/s SAR Assisted Digital Slope ADC in 28nm CMOS” ■ Acquired ILI Technology Corp. ■ MediaTek MT7615, MU-MIMO 4x4 802.11ac Wave 2 enterprise-class SoC for Wi-Fi connectivity, honored as “Innovation Product Award and R&D Accomplishment Award (Integrated Circuit)” given by Hsinchu Science Park Bureau
2015	■ Once again selected by “Thomson Reuters' Top 100 Global Innovators 2015” (the only Greater China company won the prize for second consecutive year) ■ Awarded “Outstanding Asia Pacific Semiconductor Company Award” by the GSA for the fourth consecutive year ■ Mr. Ming-Kai Tsai, MediaTek Chairman and CEO, winner of “Dr. Morris Chang Exemplary Leadership Award” awarded by GSA ■ Selected as “Taiwan Top 10 Global Brands 2015”, hosted by Ministry of Economic Affairs and Interbrand for the first time ■ MediaTek MT6795 (MediaTek Helio X10), Highly-integrated 64-bit True Octa-Core SoC, honored as “Innovation Product Award and R&D Accomplishment Award (Integrated Circuit)” given by Hsinchu Science Park Bureau ■ MediaTek Helio Chinese naming campaign received Bronze prize in “MAwards - Best Use of Social Media Promotion & Innovation Awards” ■ MediaTek Helio Chinese naming campaign won Bronze prize in “GOLDEN AWARDS - Best Use of Social Media Promotion & Innovation Awards”

Year	Milestones
	■ Won “Taiwan Corporate Sustainability Awards 2015 – Electronics Industry” Silver Medal by TAISE ■ Ranked sixth in “Top 20 Most Innovative Taiwanese Companies 2015” by Ministry of Economic Affairs, China Productivity Center and Boston Consulting Group (BCG) ■ Published 5 papers in ISSCC, and hit a new record of papers selected by ISSCC for 12 consecutive years among Taiwan companies – “A Highly Integrated Smartphone SoC Featuring a 2.5GHz Octa-Core CPU with Advanced High-Performance and Low-Power Techniques”, “An LTE SAW-less Transmitter Using 33% Duty-Cycle LO Signals for Harmonic Suppression”, “A Wideband Fractional-N Ring PLL Using a Near-Ground Pre-Distorted Switched-Capacitor Loop Filter”, “A 4.5mW CT Self-Coupled rΣ Modulator with 2.2MHz BW and 90.4dB SNDR Using Residual ELD Compensation”, and “A 0.5nJ/Pixel 4K H.265/HEVC Codec LSI for Multi-format Smartphone Applications” ■ Acquired Alpha Imaging Technology Corp. ■ Acquired Chingis Technology Corp. ■ Acquired Richtek Technology Corp.
2014	■ Named “Outstanding Asia Pacific Semiconductor Company Award” by the GSA for the third consecutive year ■ MediaTek MT6592, High Performance and Low Power True Octa-Core Heterogeneous Computing SoC, honored as “Innovation Product Award and R&D Accomplishment Award (Integrated Circuit)” given by Hsinchu Science Park Bureau ■ Selected by Thomson Reuters in “The World’s 100 Most Innovative Companies in 2014” ■ Mr. Ming-Kai Tsai, Chairman of MediaTek Inc., is honored by Harvard Business Review as one of “The Best-Performing CEOs in the World” for second consecutive years, and is the only leader from Taiwan on this list ■ Awarded “2014 Most Admired Company in Taiwan Top 3” by CommonWealth Magazine ■ Awarded seventh place in the “2014 Top 20 Taiwan Innovative Corporations” by the Ministry of Economic Affairs, China Productivity Center and BCG ■ Published 8 papers in ISSCC, not only ranked no.1 in Taiwan, but also a record high for the semiconductor industry – “Heterogeneous Multi-Processing Quad-core CPU and Dual-GPU design for optimal Performance, Power and Thermal tradeoffs in a 28nm Mobile Application Processor “, “A Digitally Assisted Self-Calibrating NFC SoC with a Triple-Mode Reconfigurable PLL and a Single-Path PICC-PCD Receiver in 110nm CMOS“, “A 2.4GHz ADPLL with Digital-Regulated Supply Noise Insensitive and Temperature Self-Compensated Ring DCO“, “A 1.89nW/0.15V self-charged XO for real-time clock generation“, “A Multi-band Inductor-less SAW-less 2G/3G Cellular Receiver in 40nm CMOS“, “A 2.667 Gb/s DDR3 Memory Interface with Asymmetric ODT on Wirebond Package and Single-Side Mounted PCB“, “A 0.29mm2 Frequency Synthesizer in 40nm CMOS with 0.19ps RMS Jitter and <-100dBc Reference Spur for 802.11ac“, and “Cloud 2.0 Clients and Connectivity 40nm CMOS with 0.19ps RMges“ ■ Acquired MStar Semiconductor, Inc. (Cayman)
2013	■ Once again won ”Outstanding Asia-Pacific Semiconductor Company Award” selected by GSA ■ Selected by Forbes Magazine in “The World’s 100 Most Innovative Companies”, and the only company in Taiwan in this list ■ Mr. Ming-Kai Tsai, Chairman & CEO of MediaTek Inc., was named in “The Best-Performing CEOs in the World” by Harvard Business Review ■ Selected as a test bed for the Wi-Fi Alliance's Wi-Fi CERTIFIED™ ac certification program ■ Awarded “2013 Most Admired Company in Taiwan Top 3” by CommonWealth Magazine ■ Published 6 papers in ISSCC, the most among Taiwan technology companies – “A Wideband Fractional-N Ring PLL with Fractional Suppression using Spectrally Shaped Segmentation”, “A 0.27mm2, 13.5dBm, 2.4GHz All-digital Polar Transmitter with 34%-Efficiency Class-D DPA in 40nm CMOS”, “An AC-Coupled Hybrid Envelope Modulator for HSUPA Transmitters with 80% Modulator Efficiency”, “A 24.7dBm All-Digital RF Transmitter for Multimode Broadband Applications in 40nm CMOS”, “A 28fj/conv-step CT Modulator with 78dB DR and 18MHz BW in 28nm CMOS Using a Highly Digital Multibit Quantizer”, and “A Universal GNSS (GPS/Galileo/Glonass/Beidou) SoC 10:15 AM with a 0.25mm2 Radio in 40nm CMOS”
2012	■ MediaTek Android smartphone platform included in the Wi-Fi CERTIFIED Passpoint™ test bed as the first and only mobile benchmark platform ■ Ralink Technology, a wholly owned subsidiary of MediaTek Inc., was selected to be in the Wi-Fi CERTIFIED WMM®-Admission Control test bed as the benchmark for advanced Wi-Fi performance and interoperability ■ MT6620, highly Integrated WiFi/BT/FM/GPS 4-in-1 SoC, honored as “2012 Innovative Product Award” by Science-based Industrial Park Administration (SIPA) ■ The winner of “Outstanding Asia-Pacific Semiconductor Company Award” selected by GSA ■ Awarded “2012 Top 10 Taiwan Innovative Corporations” by Ministry of Economic Affairs, China Productivity Center and BCG ■ Won “2012 Thomson Reuters Taiwan Innovation Awards - Top 5 Corporate Innovators in Taiwan” ■ Awarded “2012 Most Admired Company in Taiwan Top 3” by CommonWealth Magazine ■ Awarded “2012 INFO TECH TOP 100 in Asia” by Business Next magazine ■ Awarded 6th National Telecom Award 2012 – “Best Innovation in Mobile Video Technology” by CMAI Association of India ■ Mr. Ming-Kai Tsai, Chairman & CEO of MediaTek Inc., awarded as “Academician of Industrial Technology Research Institute (ITRI), R.O.C." ■ Mr. Ming-Kai Tsai, Chairman & CEO of MediaTek Inc., awarded as “The Best-Performing CEOs in the World” by Harvard Business

Year	Milestones
	Review ■ MediaTek papers selected for presentation at 2012 Symposium on VLSI Circuits- the only fabless semiconductor company to have more than two papers selected for presentation at the 2012 Symposium ■ Published papers in ISSCC – "A 4-in-1 (WiFi/BT/FM/GPS) Connectivity SoC with Enhanced Co-Existence Performance in 65nm CMOS" , and "Near Independently Regulated 5-Output Single-Inductor DC-DC Buck Converter Delivering 1.2W/mm2 in 65 nm CMOS"
2011	■ MT5395, highly-integrated 3D/Internet TV SoC, honored as "2011 The Most Innovative Product" by SIPA ■ Awarded "2011 The Best Telecommunication Technology" by CMAI Association of India ■ Awarded "The Boldness in Business" by UK Financial Times ■ Awarded Top 10 Most Admired Companies in Taiwan" by CommonWealth Magazine for ninth continuous years ■ Published five research papers in the ISSCC – "An Injection-Locked Ring PLL with Self-Aligned Injection Window", "A 70Mb/s -100.5dBm Sensitivity 65nm IP MIMO Chipset for WiMAX Portable Router (Industrial Demo)", "A Saw-Less GSM/GPRS/EDGE Receiver Embedded in a 65nm CMOS SOC (Industrial Demo)", "A Receiver for WCDMA/EDGE Mobile Phones with Inductorless Front-End in 65nm CMOS", and "A GPS/Galileo SOC with Adaptive in-Band Blocker Cancellation in 65nm CMOS" ■ Acquired Ralink Technology Corp.
2010	■ MediaTek's "WiMAX 802.16e device chipset project" awarded "Outstanding Contribution Award" by Ministry of Economic Affairs ■ Awarded "Top 50 Corporate Citizens" by CommonWealth Magazine for four continuous years ■ Awarded "Top 10 Most Admired Companies in Taiwan" by CommonWealth Magazine for 8 continuous years ■ Ranked Top 10 of "2010 Asia's 200 most-admired companies" by The Wall Street Journal ■ Awarded #12 of "Global Top 100 High-Tech Companies" by Bloomberg Business Week ■ Awarded "2010 Corporate Social Responsibility Top 65" by Global Views Monthly ■ Awarded "Best Annual Report in Taiwan" and "Best One-on-One Meetings in Taiwan" by IR Magazine ■ Published research papers in the ISSCC – "23.6 A 1V 17.9dBm 60GHz Power Amplifier"
2009	■ Awarded "Innovative Product Award" for the Company's High Sensitivity GPS SoC by SIPA ■ Awarded "Asia Pacific Leadership Council Award" by GSA ■ Awarded "Best Investor Relations by a CEO Award" and "Best Investor Relations for a Corporate Transaction" by IR Magazine ■ Awarded "Best Corporate Governance in Taiwan and in Asia" by Asiamoney Magazine ■ Awarded the third annual "Top 50 Corporate Citizens" by CommonWealth Magazine ■ Published four research papers in the ISSCC, the most among Taiwan technology companies – "A Multi-Format Blu-ray Player SOC in 90nm CMOS ", "A 1.2V 2MHz BW 0.084mm2 CT ΔΣ ADC with -97.7dBc THD and 80dB DR Using Low-Latency DEM", "A 250Mb/s-to-3.4Gb/s HDMI Receiver with Adaptive Loop Updating Frequencies and an Adaptive Equalizer", and "A 110nm RFCMOS GPS SOC with 34mW -165dBm Tracking Sensitivity"
2008	■ Awarded "Innovative Product Award" for the Company's Full-HD ATSC DTV SoC, by SIPA ■ Launched Blu-ray DVD player chipset, GSM/GPRS/EDGE handset baseband chip, and next-generation ATSC and DVB-T digital TV single-chip ■ Awarded "Best Financially Managed Company" by Fabless Semiconductor Association (FSA) for the third consecutive year ■ Awarded "Corporate Social Responsibility Award" by Global View Magazine ■ Awarded the second annual "Top 50 Corporate Citizens" by CommonWealth Magazine ■ Published seven research papers in the ISSCC, hit a new record of papers selected by ISSCC for 5 consecutive years among Taiwan companies, and was the only selected Taiwan company – "A 1V 11b 200MS/s Pipelined ADC with Digital Background Calibration in 65nm CMOS," and "A Fractional Spur Free All-Digital PLL with Loop Gain Calibration and Phase Noise Cancellation for GSM/GPRS/EDGE"
2007	■ Awarded "Distinguished Innovation Accomplishment" at the 15th ITA Award by the Ministry of Economic Affairs ■ Launched high-performance GPS signal receiver single-chip, first generation Bluetooth chip, and next-generation 120Hz video processing chip ■ Awarded "Best Financially Managed Company" by FSA for the second consecutive years ■ Awarded "The Asian Top 50" by Forbes Asia ■ Awarded "Corporate Social Responsibility Award" by Global View Magazine ■ Awarded the 12th annual "Most Admired Company in Taiwan" by CommonWealth Magazine ■ Awarded "Top 50 Corporate Citizens" by CommonWealth Magazine ■ Published research paper in the ISSCC – "RTL-based Clock recovery architecture with all-digital duty-cycle correction" ■ Published research paper in the IEEE IRPS (International Reliability Physics Symposium) "A New Device Reliability Evaluation Method for Overdrive Voltage Circuit Application"

Year	Milestones
2006	■ Awarded "Innovative Product Award" for the Company's Blu-ray DVD player chipset, by SIPA ■ Launched GSM/GPRS/EDGE high-resolution camcorder chipset for mobile phones ■ Awarded "The Asian Top 50" by Forbes Asia ■ Published research paper in the ISSCC – "Fully Integrated CMOS SoC for 56/18/16 CD/DVD-dual/RAM Applications" ■ Awarded "Best Financially Managed Company" by FSA
2005	■ Awarded "Innovative Product Award" for the Company's multimedia GSM/GPRS mobile phone chipset, by SIPA ■ Launched ATSC and DVB-T high-resolution LCD TV chipset ■ Awarded "The Asian Top 50" by Forbes Asia ■ Awarded the 10th annual "Most Admired Company in Taiwan" by CommonWealth Magazine ■ Published research papers in the ISSCC – "Multi-Format Read/Write SoC for 7x Blu-ray/16x DVD/56x CD" and "DLL-Based Clock Recovery in a PRML Channel"
2004	■ Awarded "Innovative Product Award" for the Company's DVD-Recorder Backend single-chip, by SIPA ■ Launched GSM/GPRS baseband handset chips ■ Ranked no.3 in the high-tech industry in Taiwan as part of Euromoney's "Best Corporate Governance" survey in 2004 ■ Awarded the ninth annual "Most Admired Company in Taiwan" by CommonWealth Magazine
2003	■ Awarded "Innovative Product Award" for the Company's 8x DVD-read/write (DVD-R/W) optical storage chipset, by SIPA ■ Awarded "National Quality Award" by the Executive Yuan of Taiwan R.O.C. ■ Launched DVD-Dual chipset ■ Awarded Top High-Tech Company in Taiwan by "Business Next Magazine"
2002	■ Awarded "Innovative Product Award" for the company's high-speed COMBI optical storage chipset by SIPA ■ Launched 48x CD-R/W chipset ■ Launched CD/DVD COMBI chipset
2001	■ Awarded "Innovative Product Award" for the Company's high-integration DVD-Player chipset by SIPA ■ Awarded the ninth annual MOEA Award for Industrial Technology Advancement ■ Listed on the Taiwan Stock Exchange (TSE) under the ticker of "2454"
2000	■ Awarded "Innovative Product Award" for the Company's high-speed CD-R/RW chipset by SIPA ■ Launched 12x DVD-ROM chipset
1999	■ Awarded "Innovative Product Award" for the Company's 12x DVD-ROM chipset by SIPA ■ Launched 12-x DVD-ROM chipset
1998	■ Awarded "Innovative Product Award" for the Company's CD-ROM digital data/servo processor by SIPA ■ Launched the highest performance 48x CD-ROM chipset in the world
1997	■ Founded on May 28th

organize their own classes thereby creating a strong bond amongst the community. The Company's active initiatives are expected to create positive feedback from employees and communities. Take 2018 for example, there were 5 classes organized, including art class, dance class, kids' dance class, adult yoga class and kids' science experiment class, which all received great feedback.

G. Employee Welfare Committee

MediaTek has requested each department to nominate a representative to form an Employee Welfare Committee in accordance to the Organization Regulations on the Employee Welfare Committee stipulated by the Ministry of Labor. The purpose of this committee is to oversee Employee Welfare Committee funds and to promote various benefits. MediaTek has always set aside a higher percentage of the revenue than what is stipulated by law to sponsor the Employee Welfare Committee, allowing the Committee to offer more benefits. At the same time, MediaTek has also taken cohesiveness of each department and flexible selection of personal benefits into account, such as sponsoring departmental events reimbursements and encouraging events that includes families. In 2019, MediaTek implemented flexible welfare policy for the first time, allowing employees to apply the flexibility of the subsidy to five major projects, truly reflecting the beauty and spirit of employee welfare.

H. Continuing Education and Training System

The Company provides a comprehensive training system to provide a challenging and learning environment to show employees' potential and grow the Company's overall capability. There are various types of training, each based on employee's rank and nature of work:

a. **Management Training System**: Helps managers develop their training blueprint based on skills required for their positions.
b. **Orientation**: Orientation hosted by Human Resources Department helps new staff learn company policies, corporate culture, working environment, etc. in order to fit in the workplace.
c. **General Training**: Fundamental training sessions for employees in all departments and job functions to meet regulatory and company policy requirements.
d. **Technical Engineering Training**: Provide various professional programs for engineers based on assignments they work on and different stages the Company is at.
e. **Professional Knowledge Training**: Training designed for specific profession development according to different specialty such as environmental safety, finance and accounting, human resources, information technology, intellectual property, marketing & sales, quality assurance management, etc.
f. **Personal Effectiveness Training**: Help employees utilize personal skills and knowledge, equip employees with capabilities in multiple functions and enhance working effectiveness.
g. **Language Training**: Provide different levels of English learning classes, based on employees' TOEIC scores, for them to utilize in working environment and to enhance the Company's global competitiveness.
h. **External Training**: Enhance employee quality and skills to help business development and complement insufficiency of internal trainings.

Results of education and training in the latest fiscal year are as follows:

Categories	2018				Jan. 1 to Apr. 30, 2019			
	Number of classes	Numbers of attendees	Hours	Total cost (NT$)	Number of classes	Numbers of attendees	Hours	Total cost (NT$)
Management Training System	122	2,935	18,486	34,227 thousand	17	578	3,332	10,271 thousand
General Training	125	2,293	9,406		65	841	3,489	
Professional Knowledge Training	164	7,730	25,762		23	1,242	2,376	
Personal effectiveness	93	2,388	12,145		7	232	1,194	
Language training	72	2,452	22,528		4	148	4,558	
External training	563	892	16,547		159	213	11,014	
Total	1139	18,690	104,874		275	3,254	25,963	

I. Retirement system

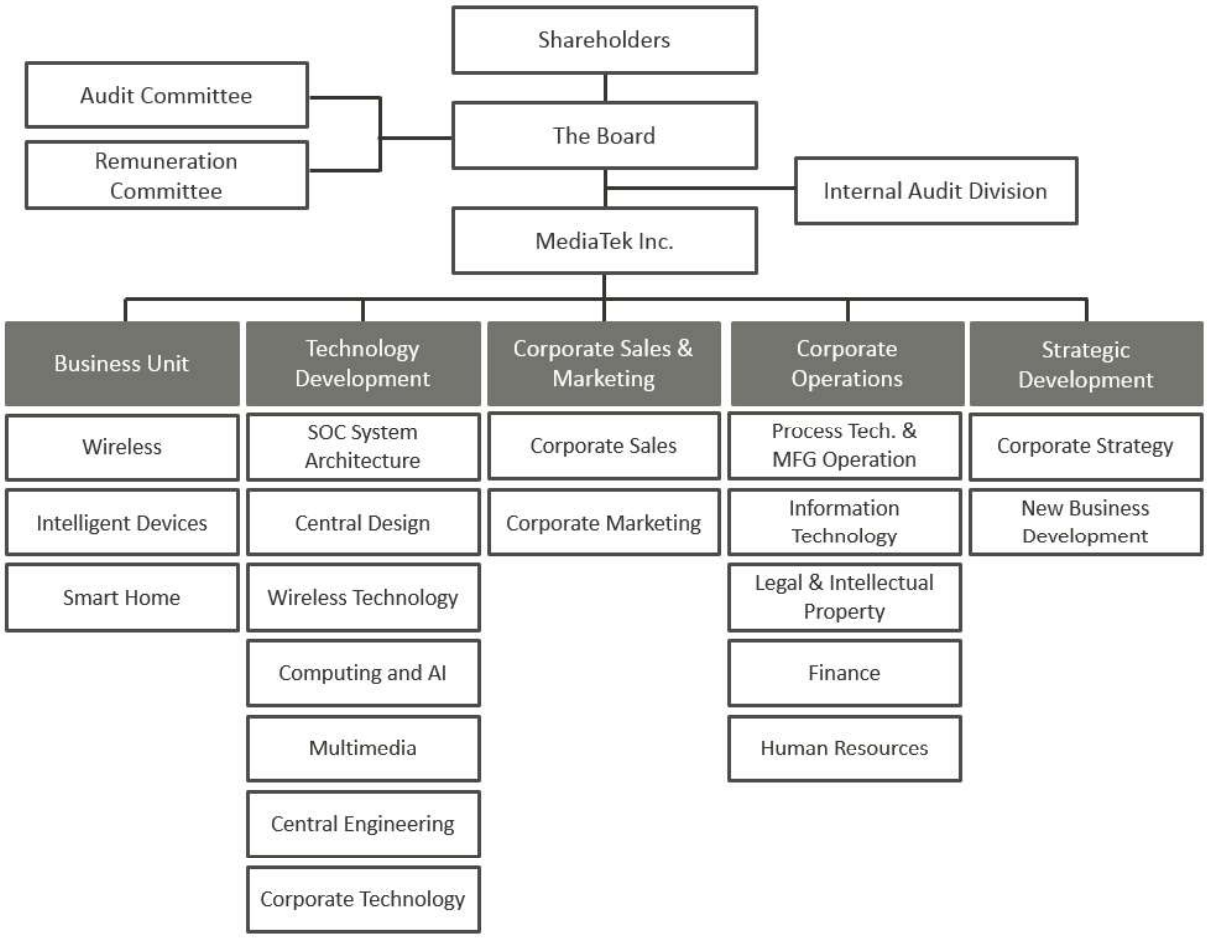
MediaTek's retirement system was designed in accordance to the Labor Standards Law and the Labor Pension Act. The retirement system makes monthly reserve deposits into the funds held at the Supervisory Committee on

III. Corporate Governance

1. Organization

1.1. Organization Chart

As of April 30, 2019



1.2. Major Corporate Functions

Department	Functions
Wireless	Research, design and promote mobile communication chips
Intelligent Devices	Research, design and promote intelligent entertainment, intelligent connectivity, intelligent display, ASIC and intelligent automotive chips
Smart Home	Research, design and promote TV business and monitor/TCON products
SOC System Architecture	Construct and plan competitive and technology-leading chips
Central Design	Integrate and implement technologies into chips, including wireless communication, computing and artificial intelligence, multimedia, analog, circuit and RF
Wireless Technology	Develop and design wireless communication core technologies, system, software, wireless communication technologies and communication system
Computing and AI	Research and develop high-efficiency computing platforms and artificial intelligence technologies
Multimedia	Research and develop video and image multimedia technologies
Central Engineering	Research and develop analog technologies in wireless communication field, including RF, audio/video, transmission interface, server and power as well as board design, high-performance circuit and advanced processor technologies
Corporate Technology	Research and develop advanced technologies and manage industry-academia collaboration
Corporate Sales	Sell products, develop customers, maintain customer relationship and manage sales operation
Corporate Marketing	Manage corporate image and promote market position
Process Tech. & MFG Operation	Pilot run products in development, develop related technologies, manage quality and reliability, manage customer satisfaction, plan production and procurements, research and develop advanced process, pilot run high-end products and develop component technologies
Information Technology	Manage information system architecture, e-commerce strategy, information system development and operation and information security
Legal & Intellectual Property	Manage corporate legal affairs, contracts, patents, and other intellectual property
Finance	Manage finance and accounting, tax, treasury and asset, strategic investments and investor relations
Human Resources	Manage human resource, organization development, general affairs, plant administration, and labor safety
Corporate Strategy	Analyze, plan and execute corporate strategies
New Business Development	Assess and assure new market opportunities
Internal Audit Division	Manage internal audit, operational procedure and information security

Assets No.	Category	Acquisition date	Description
TKBUI16020003-0	Build.&facility	2016.12.26	E棟-晶元電廠房
TKBUI10030105-0	Build.&facility	2006.07.01	MTK企業總部大樓_土建包
TKLND10100001-0	Land	2010.08.30	太陽科技廣場
TKLND19010114-0	Land	2009.01.01	台北縱橫21土地
TKBUI10030158-0	Build.&facility	2010.08.30	太陽科技廣場
TKBUI14080001-0	Build.&facility	2014.10.06	新竹市科技段222地號建物
TKBUI10030091-0	Build.&facility	2009.04.29	盟圖大樓
TKBUI19010046-0	Build.&facility	2009.02.01	縱橫21-廣義建設(87個車位)
TKBUI14040011-0	Build.&facility	2012.06.28	竹北辦公室地上建物
TKBUI19010059-0	Build.&facility	2018.02.01	台元18號8F-1～11、9F-1～2建物(計12戶，A81～A810，A91-A92)
TKBUI14040010-0	Build.&facility	2012.06.28	竹北辦公室地下停車位
TKBUI19040011-0	Build.&facility	2019.04.25	台元二街一號九樓之一、二房屋(S9)
TKBUI17120001-0	Build.&facility	2018.01.31	台元科技園區台元二街一號八樓之一、二號房屋二戶(S棟8樓)
TKLND14040004-0	Land	2012.06.28	竹北辦公室及車位的土地
TKBUI14040001-0	Build.&facility	2011.01.25	購買台元一街5號5樓--建物
TKBUI19010055-0	Build.&facility	2017.07.01	台元18號7F-1～3、5～11建物(計10戶，A1～A10)
TKLND19010126-0	Land	2018.01.01	台元18號8F-1～11、9F-1～2土地(計12戶，A81～A810，A91-A92)
TKLND14090001-0	Land	2014.08.31	文湖街18號5樓、20號5樓及停車位14個(土地)
TKBUI19010060-0	Build.&facility	2018.02.01	台元18號地下平面車位(116個)
TKBUI14070005-0	Build.&facility	2014.08.31	文湖街18號5樓、20號5樓及停車位14個(建物)
TKLND19040001-0	Land	2019.04.25	台元二街一號九樓之一、二車位及土地(S9)
TKLND18040001-0	Land	2018.04.12	台元二街一號八樓之一、二號車位及土地
TKLND14040003-0	Land	2011.01.25	購買台元一街5號5樓尾款--土地
TKBUI19010034-0	Build.&facility	2006.02.01	台元26號4F-1~3,5,16/6F-6~8/8F-3,5(32個車位)
TKLND19010123-0	Land	2017.07.01	台元18號7F-1～3、5～11土地(計10戶，A1～A10)
TKBUI10030104-0	Build.&facility	1999.06.30	研發大樓一樓
TKBUI19010057-0	Build.&facility	2018.02.01	台元18號6F-7～10建物(計4戶，A61～A64)
TKBUI15060005-0	Build.&facility	2015.07.29	台元一街5號3樓之15、16、17房屋參戶及法定、增設停車位共15位(建築物)
TKBUI19010049-0	Build.&facility	2009.12.01	台元26號5F-1~3、5F-5、15、16(15個車位)
TKBUI19010039-0	Build.&facility	2007.07.01	台元一期車位88個(26號4F-1)
TKBUI19010056-0	Build.&facility	2017.07.01	台元18號地下平面車位建物(58個)
TKLND19010103-0	Land	2006.01.01	台元26號4F-1~3,5,16/6F-6~8/8F-3,5
TKBUI14070004-0	Build.&facility	2014.08.26	台元第三期地下停車位建物款(57個)
TKLND19010125-0	Land	2018.01.01	台元18號6F-7～10土地(計4戶，A61～A64)
TKBUI19010040-0	Build.&facility	2007.12.01	台元26號8F-1,2,13,15,16
TKBUI19010036-0	Build.&facility	2006.08.01	台元26號6F-5加購67個車位
TKBUI14060001-0	Build.&facility	2014.06.27	竹北市台元一街5號3樓之18(含3車位)
TKLND19010116-0	Land	2009.11.01	台元26號5F-1~3、5F-5、15、16
TKLND19010108-0	Land	2007.12.01	台元26號8F-1,2,13,15,16<建物土
TKBUI19010044-0	Build.&facility	2008.05.01	台元26號7F-13,15,16
TKBUI19010050-0	Build.&facility	2010.06.01	台元26號4F-6~台元26號4F-9(3個車位)
TKBUI19010058-0	Build.&facility	2018.02.01	台元18號地下平面車位(26個)
TKLND19010107-0	Land	2007.06.01	台元車位88個<土地>
TKBUI19010051-0	Build.&facility	2014.05.01	台元26號5樓之6~8建物
TKBUI19010048-0	Build.&facility	2009.06.01	台元26號3F-9,10,11
TKBUI19010033-0	Build.&facility	2005.10.01	台元26號8F-6~8辦公室(9個車位)
TKBUI19010031-0	Build.&facility	2005.02.01	台元26號8F-10~12辦公室(6個車位)
TKLND15060001-0	Land	2015.07.29	台元一街5號3樓之15、16、17房屋參戶及法定、增設停車位共15位(土地)
TKBUI19010042-0	Build.&facility	2008.03.01	台元26號3F-6,7,8
TKLND19010117-0	Land	2010.05.01	台元26號4F-6~台元26號4F-9
TKLND19010105-0	Land	2006.07.01	台元26號6F-5<土地-車位>
TKLND19010124-0	Land	2017.07.01	台元18號地下平面車位土地(58個)
TKBUI19010041-0	Build.&facility	2007.12.01	台元26號8F-1,2,13,15,16車位30
TKLND19010112-0	Land	2008.04.01	台元26號7F-13,15,16建物土地
TKLND14080001-0	Land	2014.08.26	台元第三期地下停車位土地款(57個)
TKBUI19010053-0	Build.&facility	2015.03.01	台元26號6F-13建物
TKLND19010119-0	Land	2014.04.01	台元26號5樓之6~8土地
TKLND19010109-0	Land	2007.12.01	26號8F-1,2,13,15,16車位土地
TKLND19010115-0	Land	2009.05.01	台元26號3F-9,10,11
TKLND19010102-0	Land	2005.09.01	台元26號8F-6,7,8辦公室-土地
TKLND19010100-0	Land	2005.02.01	台元26號8F之10~12
TKLND19010110-0	Land	2008.02.01	台元26號3F-6,7,8建物土地
TKBUI19010045-0	Build.&facility	2008.05.01	台元26號7F-13,15,16購15個車位
TKLND19010106-0	Land	2007.05.01	713-07050489 台元街26號6樓-3
TKBUI19010035-0	Build.&facility	2006.08.01	台元26號6F-5
TKBUI19010032-0	Build.&facility	2005.06.01	台元26號8F-9辦公室(3個車位)
TKBUI19010047-0	Build.&facility	2009.05.01	Korea Dormitory
TKLND19010121-0	Land	2015.03.01	台元26號6F-13土地
TKBUI19010037-0	Build.&facility	2007.05.01	台元26號6F-3
TKLND19010113-0	Land	2008.04.01	台元26號7F-13,15,16車位土地
TKBUI19010043-0	Build.&facility	2008.03.01	台元26號3F-6,7,8加購車位7個
TKLND19010104-0	Land	2006.07.01	台元26號6F-5<土地-建物>
TKLND19010101-0	Land	2005.06.01	台元26號8F-9辦公室-土地
TKBUI19010052-0	Build.&facility	2014.05.01	台元26號地下平面車位建物(5個)
TKBUI19010038-0	Build.&facility	2007.05.01	台元26號6F-3加購3個車位
TKLND19010111-0	Land	2008.02.01	台元26號3F-6,7,8車位土地
TKBUI19010054-0	Build.&facility	2015.03.01	台元26號6F-13 B2平面車位3個
TKLND19010120-0	Land	2014.04.01	台元26號地下平面車位土地(5個)
TKLND19010122-0	Land	2015.03.01	台元26號6F-13車位土地